

contribute directly to system Bit Error Rate (BER). Most DECT system designers have settled on an upper limit of allocation to the SAW filter group delay ripple at 300nS.

The choice is all the more complicated by the fact that SAW fillers can be realised in fundamentally one of two different ways: as Resonator filters or as Transversal filters. A comparison of the relative performance of SAW resonator and transversal filters is given in Table 1.

In brief, SAW Resonators can provide DECT system designs with low insertion loss filters hence reducing the gain and associated current consumption. This is achieved however at considerable expense overall on the system performance and manufacturability. Group delay ripple for a DECT based design resonator filter is typically five to ten times higher than that for a typical transversal filter at ambient. This figure can degrade further under full operating temperature conditions and time; matching impedances are highly sensitive; impedance matching networks are complicated by the need commonly to interface into an unbalanced mixer; co-channel rejection can be marginal against specification over the operating temperature range.

Saw bi-directional transversal filters on the other hand have an insertion loss of typically 14-16dB, and may require additional gain. However the filter has many compensating features including:

1. Excellent co-channel characteristics
2. Time and temperature stable matching impedances permitting simple, single element, fixed value matching components
3. Option for balanced or unbalanced drive networks
4. Exceptionally low group delay ripple
5. Operation over either the full or extended DECT temperature range
6. Good third order intercept point

In conclusion, Dynex Semiconductor recommend the adoption of a ST cut Quartz Transversal filter - DW9249 for use as an 112.32MHz IF filter in DECT receivers.

	ADVANTAGES	DISADVANTAGES
TRANSVERSAL FILTER DESIGN	<p>V.Low Group Delay Ripple</p> <p>Stable Matching Impedances</p> <p>Balanced/Unbalanced Drive</p> <p>Good Stopband Rejection</p>	<p>Increased Insertion Losses</p> <p>Restricted Minimum Fraction</p> <p>Bandwidth >0.3%</p> <p>Increased Size</p>
RESONATOR FILTER DESIGN	<p>V.Low Insertion Loss</p> <p>V.Narrow Fractional Bandwidths</p> <p>Good Co-Channel Selectivity</p>	<p>V.Poor Group Delay Ripple</p> <p>Unbalanced Drive Option Only</p> <p>Mediocre Stop Band Rejection</p>

Table 1: SAW Filter Technology Comparison

CIRCUIT MATCHING NETWORK:

Significantly, the SAW filter is designed asymmetric with the input and output impedances configured independently. Furthermore, the SAW frequency response is purposefully designed to have an asymmetric amplitude characteristic when measured unmatched in 50 ohms, but a symmetric amplitude when appropriately matched into the correct impedances. Two options for matching configurations are presented here:

1. Input: 50 ohms / Unbalanced drive
Output: High Impedance IF Downconversion chip / Balanced drive

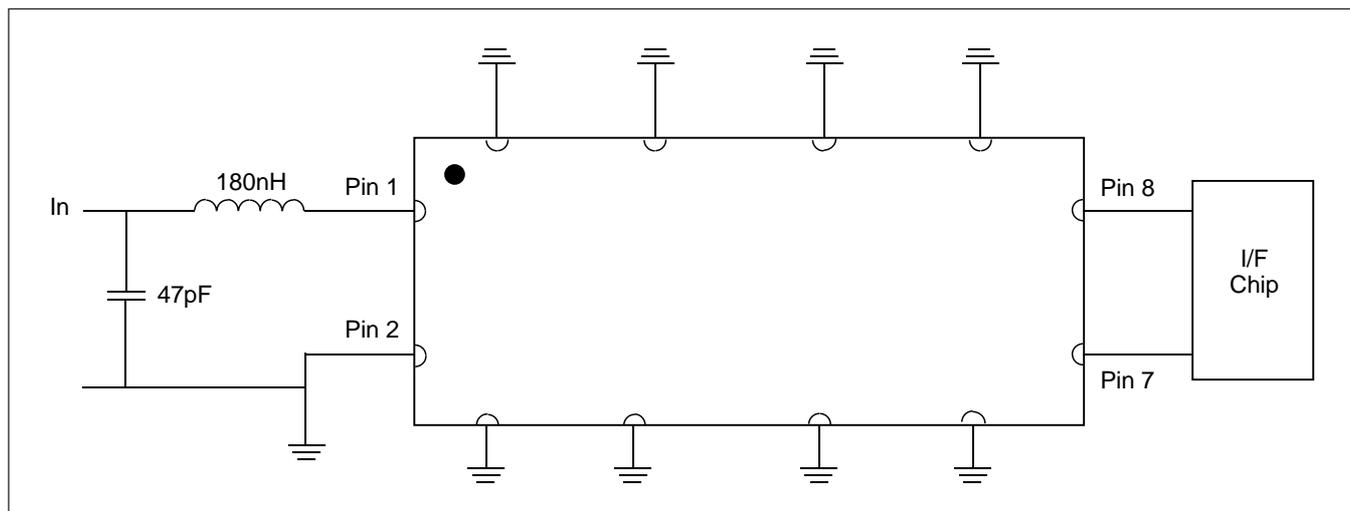


Figure 2

2. Input: 50 ohms / Unbalanced
Output: 50 ohms / Unbalanced drive

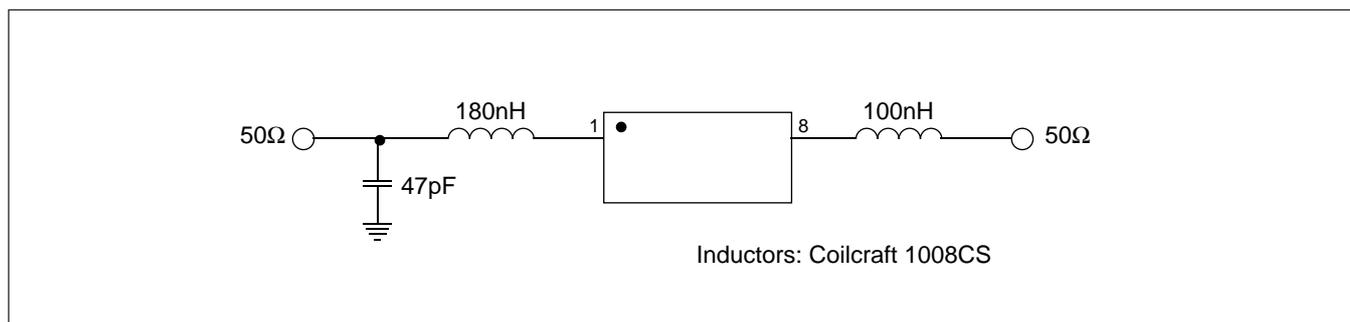
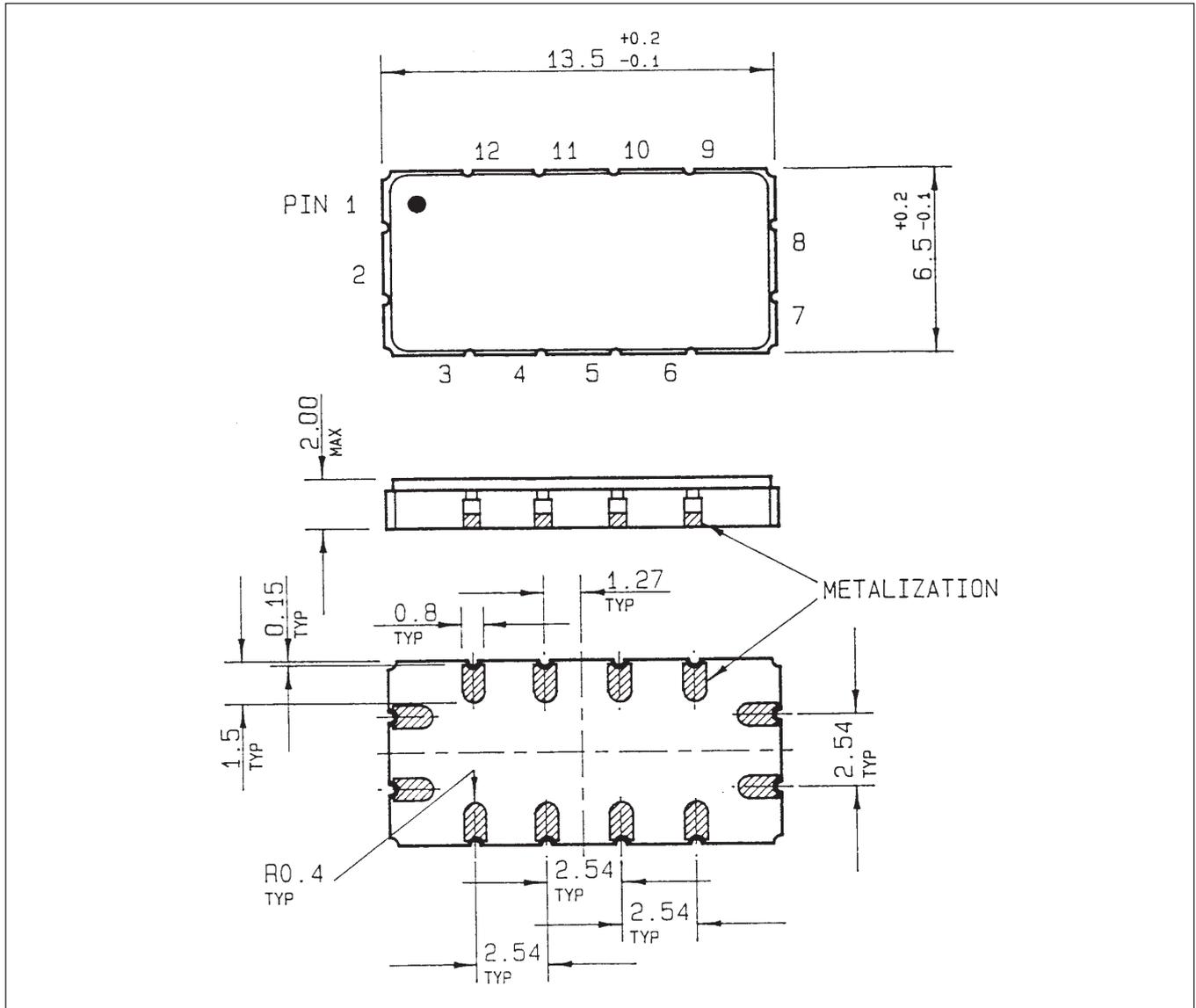


Figure 3

PACKAGE DETAILS



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